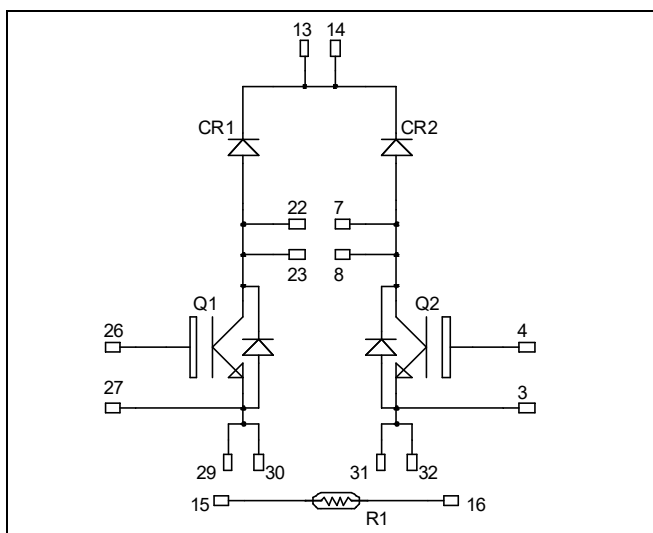


Dual Boost chopper Trench + Field Stop IGBT4 Power module

$V_{CES} = 1200V$
 $I_C = 90A @ T_c = 80^\circ C$



Application

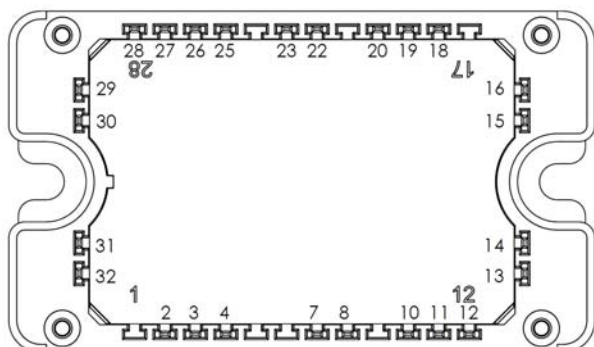
- AC and DC motor control
- Switched Mode Power Supplies
- Power Factor Correction

Features

- **Trench + Field Stop IGBT 4**
 - Low voltage drop
 - Low leakage current
 - Low switching losses
 - Low leakage current
 - RBSOA and SCSOA rated
- Kelvin emitter for easy drive
- Very low stray inductance
- Internal thermistor for temperature monitoring

Benefits

- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Solderable terminals both for power and signal for easy PCB mounting
- Low profile
- Easy paralleling due to positive TC of V_{CEsat}
- Each leg can be easily paralleled to achieve a single boost of twice the current capability
- RoHS compliant



All multiple inputs and outputs must be shorted together
 Example: 13/14 ; 29/30 ; 22/23 ...

All ratings @ $T_j = 25^\circ C$ unless otherwise specified

Absolute maximum ratings (per IGBT)

Symbol	Parameter	Max ratings	Unit
V_{CES}	Collector - Emitter Voltage	1200	V
I_C	Continuous Collector Current	$T_c = 25^\circ C$	A
		$T_c = 80^\circ C$	
I_{CM}	Pulsed Collector Current	$T_c = 25^\circ C$	150
V_{GE}	Gate - Emitter Voltage	± 20	V
P_D	Power Dissipation	$T_c = 25^\circ C$	385
RBSOA	Reverse Bias Safe Operating Area	$T_j = 150^\circ C$	150A @ 1150V

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

Electrical Characteristics (per IGBT)

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
I_{CES}	Zero Gate Voltage Collector Current	$V_{GE} = 0V$; $V_{CE} = 1200V$			250	μA
$V_{CE(sat)}$	Collector Emitter Saturation Voltage	$V_{GE} = 15V$ $I_C = 75A$		$T_J = 25^\circ C$ $T_J = 150^\circ C$	1.85 2.25	V
$V_{GE(th)}$	Gate Threshold Voltage	$V_{GE} = V_{CE}$, $I_C = 3mA$	5	5.8	6.5	V
I_{GES}	Gate – Emitter Leakage Current	$V_{GE} = 20V$, $V_{CE} = 0V$			600	nA

Dynamic Characteristics (per IGBT)

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
C_{ies}	Input Capacitance	$V_{GE} = 0V$ $V_{CE} = 25V$ $f = 1MHz$		4.4		nF
C_{oes}	Output Capacitance			0.29		
C_{res}	Reverse Transfer Capacitance			0.24		
Q_G	Gate charge	$V_{GE} = \pm 15V$; $V_{CE} = 600V$ $I_C = 75A$		0.57		μC
$T_{d(on)}$	Turn-on Delay Time	Inductive Switching ($25^\circ C$) $V_{GE} = \pm 15V$ $V_{Bus} = 600V$ $I_C = 75A$ $R_G = 2.2\Omega$		130		ns
T_r	Rise Time			20		
$T_{d(off)}$	Turn-off Delay Time			300		
T_f	Fall Time			45		
$T_{d(on)}$	Turn-on Delay Time	Inductive Switching ($150^\circ C$) $V_{GE} = \pm 15V$ $V_{Bus} = 600V$ $I_C = 75A$ $R_G = 2.2\Omega$		150		ns
T_r	Rise Time			35		
$T_{d(off)}$	Turn-off Delay Time			350		
T_f	Fall Time			80		
E_{on}	Turn-on Switching Energy	$V_{GE} = \pm 15V$ $V_{Bus} = 600V$ $I_C = 75A$ $R_G = 2.2\Omega$	$T_J = 25^\circ C$ $T_J = 150^\circ C$	3.3 8.5		mJ
E_{off}	Turn-off Switching Energy		$T_J = 25^\circ C$ $T_J = 150^\circ C$	4.2 7.2		mJ
I_{sc}	Short Circuit data	$V_{GE} \leq 15V$; $V_{Bus} = 900V$ $t_p \leq 10\mu s$; $T_J = 150^\circ C$		300		A
R_{thJC}	Junction to Case Thermal Resistance				0.39	$^\circ C/W$

Chopper diode ratings and characteristics (per diode)

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
V_{RRM}	Peak Repetitive Reverse Voltage				1200	V
I_{RM}	Reverse Leakage Current	$V_R = 1200V$			100	μA
I_F	DC Forward Current	$T_c = 80^\circ C$		100		A
V_F	Diode Forward Voltage	$I_F = 100A$		2.4	3	V
		$I_F = 150A$		2.7		
		$I_F = 100A$, $T_J = 125^\circ C$		1.8		
t_{rr}	Reverse Recovery Time	$I_F = 100A$ $V_R = 800V$ $di/dt = 200A/\mu s$	$T_J = 25^\circ C$	385		ns
			$T_J = 125^\circ C$	480		
Q_{rr}	Reverse Recovery Charge		$T_J = 25^\circ C$	1055		nC
			$T_J = 125^\circ C$	5240		
R_{thJC}	Junction to Case Thermal Resistance				0.55	$^\circ C/W$

Thermal and package characteristics

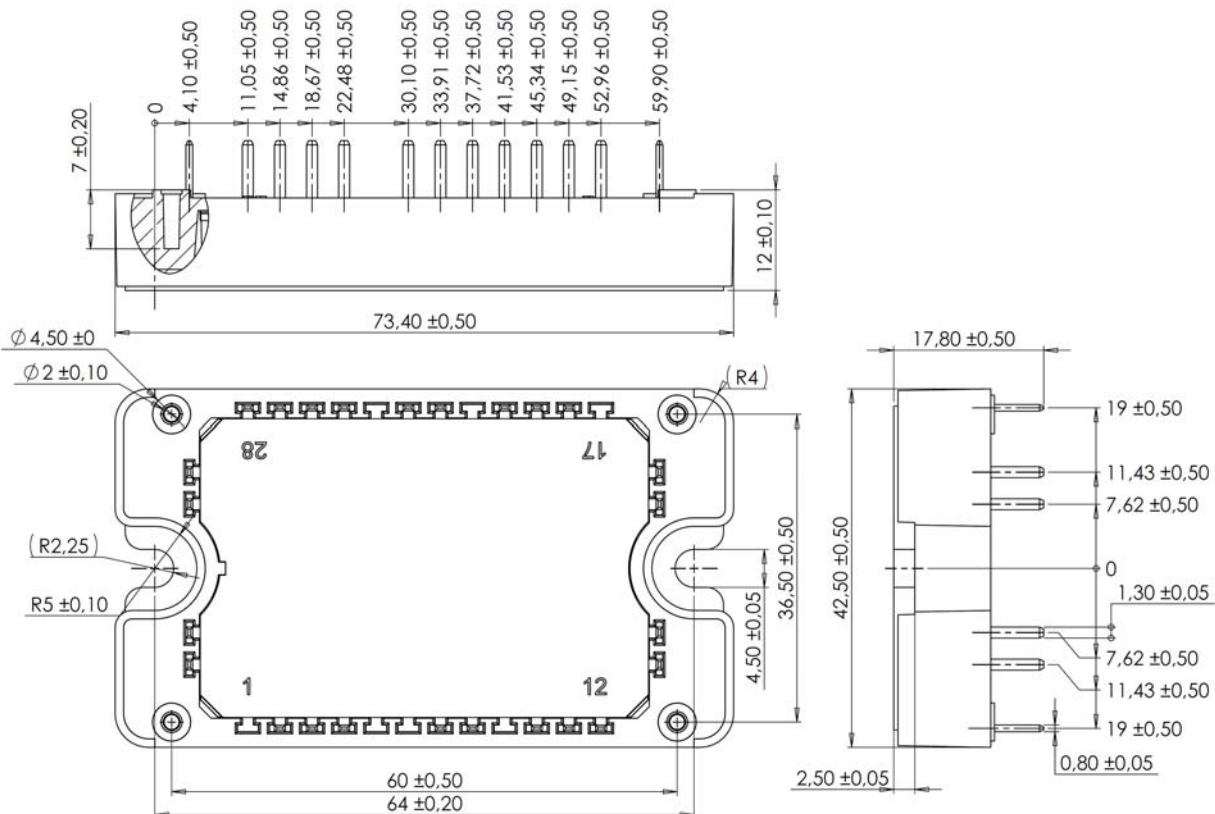
Symbol	Characteristic				Min	Max	Unit
V _{ISOL}	RMS Isolation Voltage, any terminal to case t =1 min, 50/60Hz				4000		V
T _J	Operating junction temperature range				-40	175	°C
T _{JOP}	Recommended junction temperature under switching conditions				-40	T _J max -25	
T _{STG}	Storage Temperature Range				-40	125	
T _C	Operating Case Temperature				-40	125	
Torque	Mounting torque	To heatsink	M4	2	3	N.m	
Wt	Package Weight					110	g

Temperature sensor NTC (see application note APT0406 on www.microsemi.com for more information).

Symbol	Characteristic	Min	Typ	Max	Unit
R ₂₅	Resistance @ 25°C		50		kΩ
ΔR ₂₅ /R ₂₅			5		%
B _{25/85}	T ₂₅ = 298.15 K		3952		K
ΔB/B	T _C = 100°C		4		%

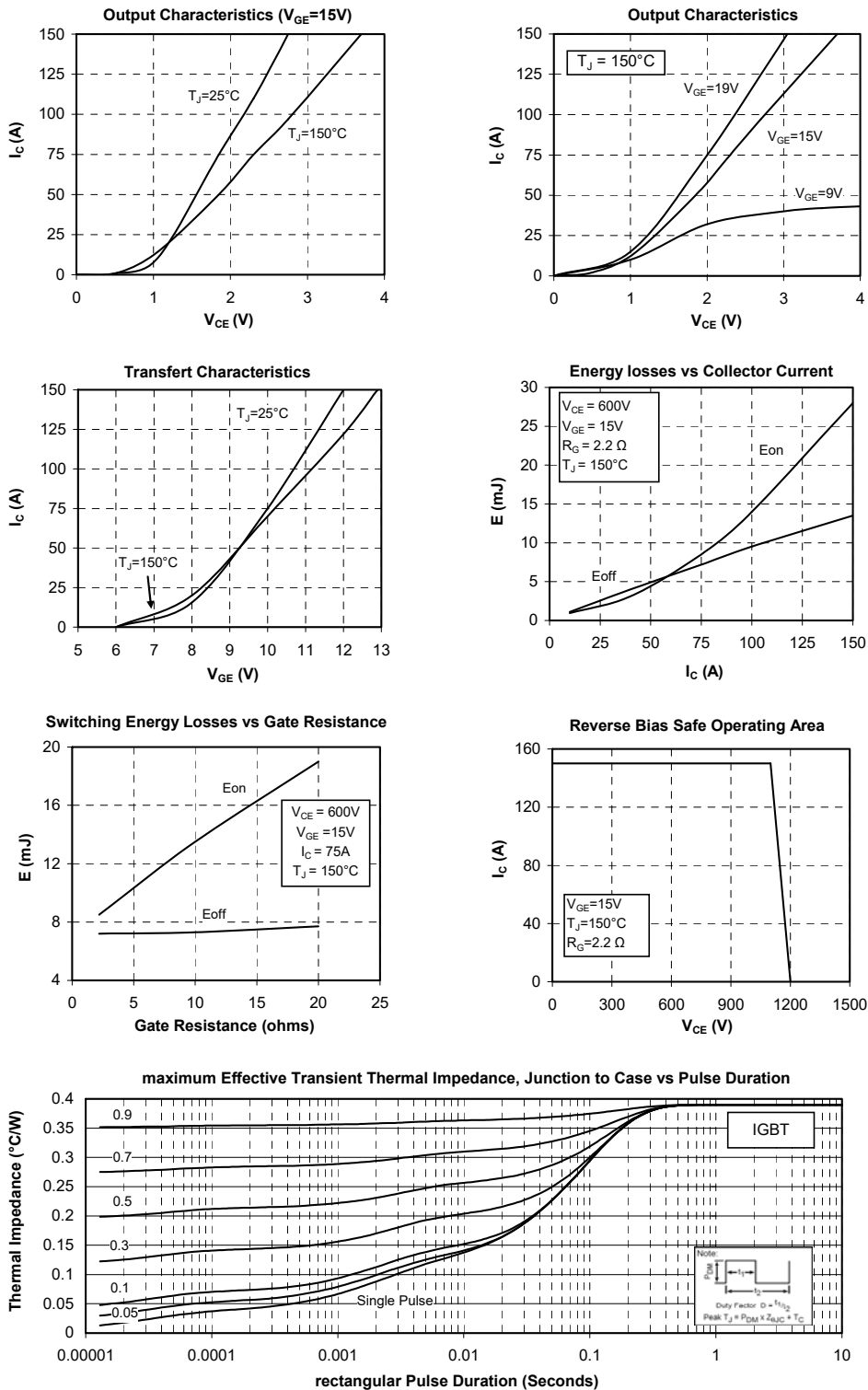
$$R_T = \frac{R_{25}}{\exp \left[B_{25/85} \left(\frac{1}{T_{25}} - \frac{1}{T} \right) \right]}$$

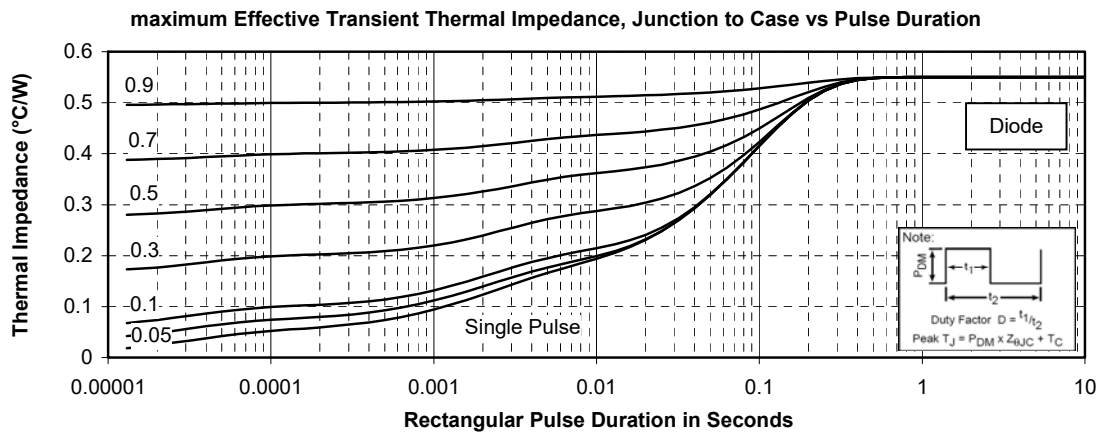
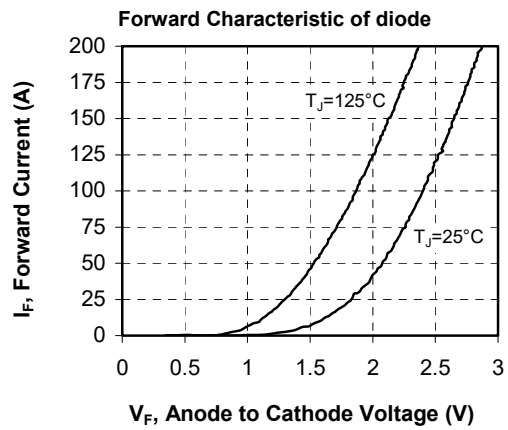
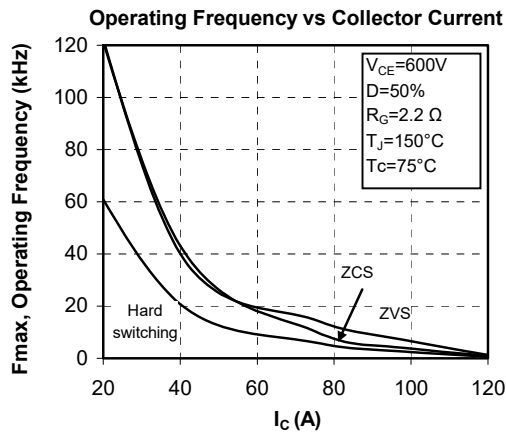
Package outline (dimensions in mm)



See application note 1906 - Mounting Instructions for SP3F Power Modules on www.microsemi.com

Typical Performance Curve





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